



FAN301 PWM Controller for Low Standby Power Charger Applications

Features

- Ultra-Low Standby Power Under 20mW at 264V_{AC}
- Constant-Current (CC) Control without Secondary-Feedback Circuitry
- Green Mode: PWM Frequency Linearly Decreasing
- Fixed PWM Frequency at 45kHz with Frequency Hopping to Solve EMI Problems
- High-Voltage Startup
- Low Operating Current: 3mA
- Peak-Current-Mode Control in CV Mode
- Cycle-by-Cycle Current Limiting
- V_{DD} Over-Voltage Protection (Auto-Restart)
- V_{DD} Under-Voltage Lockout (UVLO)
- Gate Output Maximum Voltage Clamped at 15V
- Fixed Over-Temperature Protection (Auto-Restart)

Applications

- Battery chargers for cellular phones, cordless phones, PDA, digital cameras, power tools
- Replaces linear transformer and RCC SMPS

Description

This highly integrated PWM controller, FAN301, provides features to enhance the performance of low-power flyback converters. The proprietary topology enables simplified circuit design for battery charger applications. A low-cost, smaller, and lighter charger is the result, compared to a conventional design or a linear transformer.

To minimize standby power consumption, a proprietary green-mode function provides off-time modulation to linearly decrease PWM frequency under light-load conditions. This green mode assists the power supply in meeting power conservation requirements.

By using FAN301, a charger can be implemented with fewer external components and minimized cost. A typical output CV/CC characteristic envelope is shown in Figure 1.

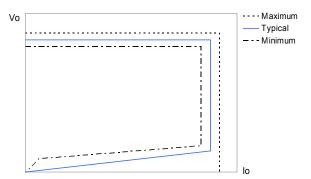


Figure 1. Typical Output V-I Characteristic (without Cable)

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	
FAN301MY	-40°C to +105°C	8-Lead, Small Outline Package	Tape & Reel	

Application Diagram

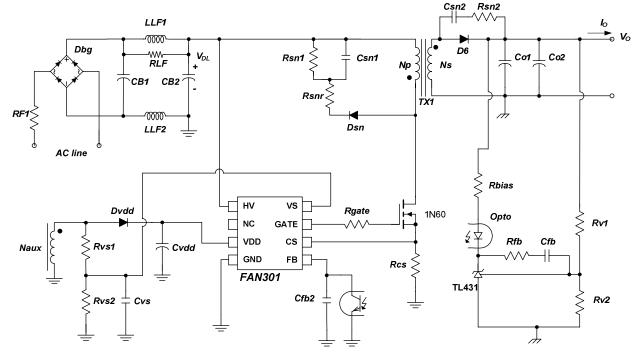
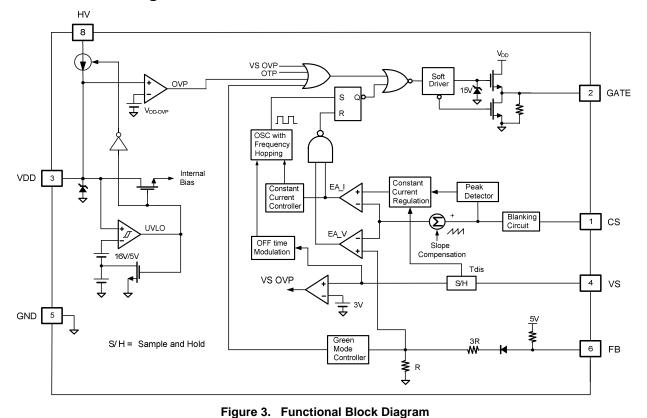


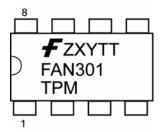
Figure 2. Typical Application

Internal Block Diagram



© 2008 Fairchild Semiconductor Corporation FAN301 • Rev. 1.0.0

Marking Information



F- Fairchild Logo

Z: Assembly Plant Code

X: Year Code

Y: Week Code

TT: Die-Run Code

T: M=SOP

P: Y= Green Package

M: Manufacture Flow Code

Figure 4. Top Mark

Pin Configuration

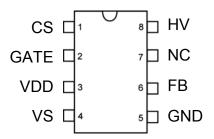


Figure 5. Pin Configuration

Pin Definitions

Pin#	Name	Description
1	CS	Current sense. Connected to a current-sense resistor for peak-current-mode control in CV mode. The current-sense signal is also provided for output-current regulation in CC mode.
2	GATE	The totem-pole output driver to drive the power MOSFET.
3	VDD	Power supply
4	VS	Feedback. The VS pin provides feedback information for output-current regulation in CC mode.
5	GND	Power ground
6	FB	Feedback. The FB pin provides feedback information to the internal PWM comparator. This feedback is used to control the duty cycle.
7	NC	No connection
8	HV	For startup. This pin is pulled HIGH to the line input or bulk capacitor via resistors.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter			Max.	Unit
V _{HV}	HV Pin Input Voltage			500	V
V _{VDD}	DC Supply Voltage ^{(1) (2)}	DC Supply Voltage ^{(1) (2)}			V
V _{VS}	VS Pin Input Voltage		-0.3	7.0	V
Vcs	CS Pin Input Voltage		-0.3	7.0	V
V_{FB}	FB Pin Input Voltage			7.0	V
P_D	Power Dissipation (T _A =25°C)			660	mW
heta JA	Thermal Resistance (Junction to Air)			150	°C/W
heta JC	Thermal Resistance (Junction to Case)			39	°C/W
TJ	Operating Junction Temperature			150	°C
T _{STG}	Storage Temperature Range			150	°C
TL	Lead Temperature (Wave Soldering or IR, 10 Seconds)				°C
ESD	Flacture static Disabours Conchilit.	Human Body Model: JEDEC:JESD22_A114	5.50		kV
	Electrostatic Discharge Capability ⁽³⁾ Charged Device Model: JEDEC:JESD22_ATT		1.75		N.V

Notes:

- 1. All voltage values, except differential voltages, are given with respect to GND pin.
- 2. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.
- 3. All pins excluding HV pin. All pins including HV pin: HBM=1000V, CDM=750V

Electrical Characteristics

 V_{DD} =15V, TA=25°C, unless noted.

Symbol		Parameter	Conditions	Min.	Тур.	Max.	Units
HV Section	1			•		•	
$V_{\text{HV-MIN}}$	Minimum Sta	artup Voltage on HV Pin				50	V
I _{HV}	Supply Curre	ent Drawn from HV Pin	V _{AC} =90V; V _{DD} =0V, Controller Off		1.5	2.0	mA
I _{HV-LC}	Leakage Cui	rrent Drawn from HV Pin	With Auxiliary Supply; V _{HV} =500V, V _{DD} =15V, Controller on		0.8	3.0	μA
VDD Section	on						
V _{OP}	Continuously	y Operation Voltage				25	V
$V_{\text{DD-ON}}$	Turn-On Thr	eshold Voltage			16		V
V_{DD-OFF}	Turn-Off Thr	eshold Voltage			5		V
I _{DD-ST}	Startup Curr	ent	V _{DD} =V _{DD-ON} – 0.16V		450		μΑ
I _{DD-OP}	Operating Su	upply Current	V _{DD} =20V, f=f _{OSC} , C _L =1nF		3		mA
I _{DD-BURST}	Burst-Mode	Operating Supply Current	V _{DD} =20V, C _L =1nF		200		μA
V _{DD-OVP}	V _{DD} Over-Vo	oltage Protection Level	Auto-Restart	27	28	29	V
t _{D-VDDOVP}		Itage Protection	f=45kHz		100		μs
Oscillator	Section			·	•		•
	_	Center Frequency		41	45	49	
f _{OSC}	Frequency	Hopping Range			±1.55		kHz
t _{FHR}	Frequency H	lopping Period			2.84		ms
f _{OSC-G}	Green-Mode	Frequency			20		kHz
fosc-cm-min		equency if CCM Current Mode)			21.5		kHz
f _{OSC-CCM}	Minimum Fre	equency in CC Mode urrent Mode)			24.5		kHz
Feedback i	input Section	1		I.			ı
Av	FB Input to Current Comparator Attenuation				1/3		V/V
Z _{FB}	Input Impedance				42		kΩ
Z _{FB-BURST}	1 1				49.5		kΩ
V _{FB-OPEN}	Output High Voltage		FB Pin Open	5.0	5.3		V
V _{FB-N}	Green-Mode Entry Voltage				3		V
V_{FB-G}	Green-Mode Ending Voltage				2.4		V
V_{FBL}	Enter Zero D	Outy Cycle of FB Voltage			1.4		V
V_{FBH}	Exit Zero Du	ty Cycle of FB Voltage			1.5		V

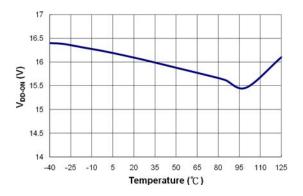
Continued on the following page...

Electrical Characteristics (Continued)

 V_{DD} =15V, T_A =25°C, unless noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Voltage-Se	nse Section	•				•
I _{TC}	Bias Current	V _{CS} =5V	9	10	11	μΑ
V _{VS-CM-MIN}	Minimum V _S Threshold Voltage of ZCD Undetectable Protection			0.55		V
V _{VS-CM-MAX}	Maximum V _S Threshold Voltage of ZCD Undetectable Protection			0.75		V
V _{VS-BLANK}	ZCD Blanking Time			2.45		μs
V _{VS-UVP}	Brownout Protection Voltage			0.685		V
V _{VS-OFFSET}	ZCD Turn-Off Threshold		100	200	300	mV
V _{VS-OVP}	Output Over-Voltage Protection			3		V
t _{VS-OVP}	Output Over-Voltage Protection Debounce Time	f=45kHz		240		μs
Current-Se	nse Section					
V_{VR}	Reference Voltage		2.475	2.500	2.525	V
V _{CCR}	Variation Test voltage on CS Pin for Constant Current Output	V _{CS} =0.47V		2.43		V
V _{SN-CC}	Starting Voltage of Frequency Decreasing of CC	V _{CS} =5V, f _{S1} =f _{OSC} -2KHz		2.1		V
$V_{\text{SG-CC}}$	Ending Voltage of Frequency Decreasing of CC	V_{CS} =5V, f_{S2} = f_{OSC} +2KHz		0.76		V
S _{G-CC}	Frequency Decreasing Rate of CC	S_{G-CC} = $(f_{S1}$ - $f_{S2})/(V_{FBN-CC}$ - V_{FBG-CC}	10.00	12.75	15.00	Hz/m\
V_{STH}	Threshold Voltage for Current Limit			0.8		V
$V_{\text{STH-VA}}$	Threshold Voltage for Current Limit when ZCD undetectable	V _{VS} =0.3V, V _{COMV} =5V		0.3		V
t_{PD}	Propagation Delay to GATE Output			180		ns
t _{MIN}	Minimum On Time	V _{VS} =-0.5V, V _{CS} =1.5V		530		ns
t_{LEB}	Leading Edge Blanking Time			350		ns
V_{SLOPE}	Slope Compensation	Maximum Duty		0.3		V
GATE Sect	ion					
DCY_{MAX}	Maximum Duty Cycle		54	57	60	%
$V_{\text{GATE-L}}$	Output Voltage Low	V _{DD} =25V, I _O =10mA			1.5	٧
V_{GATE-H}	Output Voltage High	V _{DD} =8V, I _O =1mA	5			V
V_{GATE-H}	Output Voltage High	V_{DD} =5.5V, I_{O} =1mA	4			V
$V_{\text{MOS-OFF}}$	Output Voltage Turn-Off Voltage		8.9	9.5	10.1	٧
V _{MOS-ON}	Output Voltage Turn-On Voltage		6.9	7.5	8.1	V
t _r	Rising Time	V _{DD} =25V, C _L =1nF		140		ns
t _f	Falling Time	V _{DD} =25V, C _L =1nF		50		ns
V _{GATE-CLAMP}	Output Clamp Voltage	V _{DD} =25V	14	15	18	V
Over-Temp	erature-Protection Section					
T _{OTP}	Threshold Temperature for Over-Temperature Protection			140		°C
T _{OTP} -	Restart Threshold Temperature for Over-Temperature Protection			110		°C

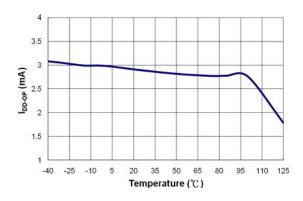
Typical Performance Characteristics



5.2 5.1 5.1 4.9 4.8 4.7 4.6 -40 -25 -10 5 20 35 50 65 80 95 110 125 Temperature (°C)

Figure 6. Turn-on Threshold Voltage ($V_{DD\text{-}ON}$) vs. Temperature

Figure 7. Turn-off Threshold Voltage (V_{DD-OFF}) vs. Temperature



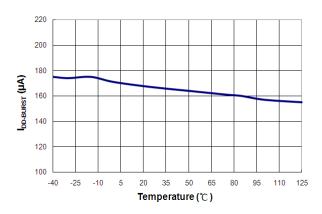
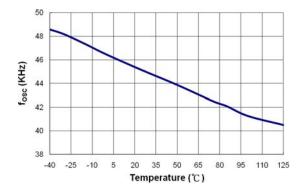


Figure 8. Operating Supply Current (I_{DD-OP}) vs. Temperature

Figure 9. Burst-mode Operating Supply Current (I_{DD-BURST}) vs. Temperature



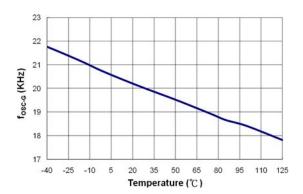
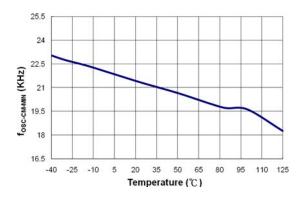


Figure 10. Center Frequency (fosc) vs. Temperature

Figure 11. Green-Mode Frequency (f_{OSC-G}) vs. Temperature

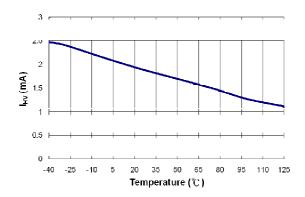
Typical Performance Characteristics (Continued)



62 60 58 DCYMAX (%) 54 52 -40 -25 -10 20 35 50 65 80 110 Temperature (°C)

Figure 12. Minimum Frequency if CCM (fosc-cm-Min) vs. Temperature

Figure 13. Maximum Duty Cycle (DCY_{MAX}) vs. Temperature



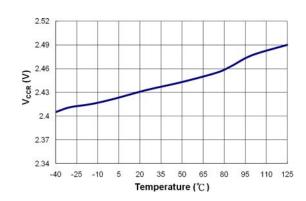
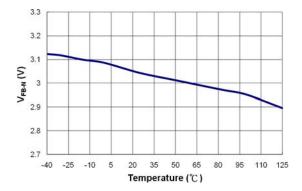


Figure 14. Supply Current Drawn from HV Pin (I_{HV}) vs. Temperature

Figure 15. Variation Test Voltage on CS Pin for Constant Current Output (V_{CCR}) vs. Temperature



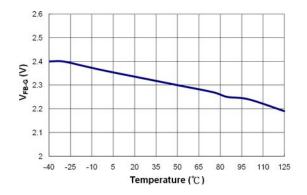
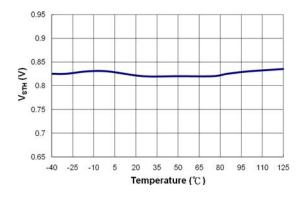


Figure 16. Green-Mode Entry Voltage (V_{FB-N}) vs. Temperature

Figure 17. Green-Mode Exit Voltage (V_{FB-G}) vs. Temperature

Typical Performance Characteristics (Continued)



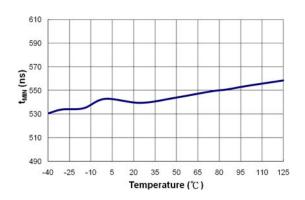
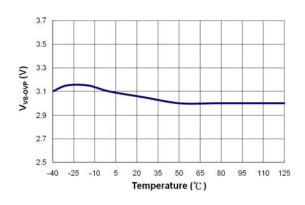


Figure 18. Threshold Voltage for Current Limit (V_{STH}) vs. Temperature

Figure 19. Minimum On Time (t_{MIN}) vs. Temperature



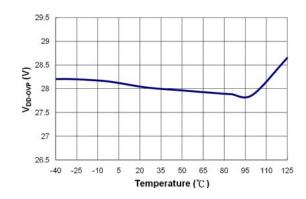
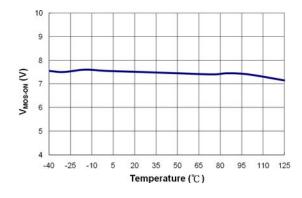


Figure 20. Output Over-Voltage Protection (V_{VS-OVP}) vs. Temperature

Figure 21. V_{DD} Over-Voltage Protection Level (V_{DD-OVP}) vs. Temperature



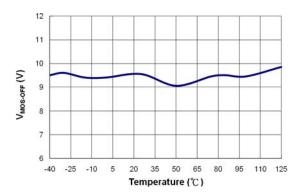


Figure 22. Output Voltage Turn-On Voltage (V_{MOS-OFF}) Figure 23. Output Voltage Turn-Off Voltage (V_{MOS-OFF}) vs. Temperature

vs. Temperature

Operation Description

The FAN301H is an innovative ultra-low standby power IC with Constant Voltage (CV) / Constant Current (CC).

When the system operates in CV mode, PWM duty modulation is controlled by the FB pin, which receives a secondary-side signal through an opto-coupler.

When the system changes to CC mode, the proprietary Primary Side Regulation (PSR) topology simplifies circuit design without secondary feedback circuitry, especially for battery charger applications. The CC mode achieved through Fairchild's PSR technique uses a mixed signal algorithm to detect the primary-side current and sampling the voltage through primary-side auxiliary winding, then calculates the average current on the secondary side.

Figure 24 shows the basic circuit diagram of a flyback converter with typical waveforms shown in Figure 25. Generally, discontinuous conduction mode (DCM) operation is preferred for constant-current control since it allows better output regulation. The operation principles of DCM flyback converter are as follows:

During the MOSFET on time (t_{ON}), input voltage (V_{DL}) is applied across the primary-side inductor (L_m). Then MOSFET current (I_{ds}) increases linearly from zero to the peak value (I_{pk}). During this time, the energy is drawn from the input and stored in the inductor.

When the MOSFET is turned off, the energy stored in the inductor forces the rectifier diode (D) to be turned on. While the diode is conducting, the output voltage (V_0) , together with diode forward-voltage drop (V_F) , is applied across the secondary-side inductor $(L_m \times N_s^2/N_\rho^2)$ and the diode current (I_D) decreases linearly from the peak value $(I_{pk} \times N_p/N_s)$ to zero. At the end of inductor current discharge time (t_{DIS}) , all the energy stored in the inductor has been delivered to the output.

When the diode current reaches zero, the transformer auxiliary winding voltage (V_w) begins to oscillate by the resonance between the primary-side inductor (L_m) and the effective capacitor loaded across MOSFET.

During the inductor current discharge time, the sum of output voltage and diode forward-voltage drop is reflected to the auxiliary winding side as $(V_0+V_F) \times$ N_a/N_s . This voltage signal is proportional to the secondary winding, so it provides the controller the feedback signal from the secondary side and achieves a constant voltage output property. In constant current output operation, this voltage signal is detected and examined by the precise constant-current regulation controller. The on-time of the MOSFET is determined to control input power and provide a constant current output property. With feedback voltage V_{CS} across the current-sense resistor, the controller can obtain the input power of power supply. Therefore, the region of constant-current output operation can be adjusted by a current-sense resistor.

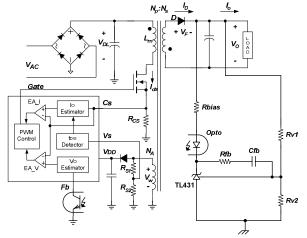


Figure 24. Simplified Flyback Converter Circuit

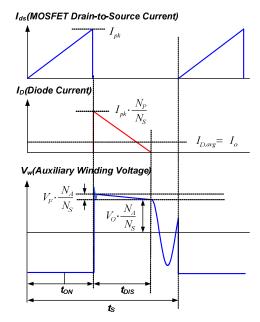


Figure 25. Key Waveforms of DCM Flyback Converter

High-Voltage Startup

Figure 26 shows the HV-startup circuit for FAN301 applications. The HV pin is connected to the line input or bulk capacitor through a resistor, R_{START} (100k Ω is recommended). During startup, the internal startup circuit is enabled. Meanwhile, line input supplies the current, I_{STARTUP} , to charge the hold-up capacitor, C_{DD} , through R_{START} . When the V_{DD} voltage reaches $V_{\mathsf{DD-ON}}$, the internal startup circuit is disabled, blocking I_{STARTUP} from flowing into the HV pin. Once the IC turns on, C_{DD} is the only energy source to supply the IC consumption current before the PWM starts to switch. Thus, C_{DD} must be large enough to prevent V_{DD} from dropping to $V_{\mathsf{DD-OFF}}$ before the power can be delivered from the auxiliary winding.

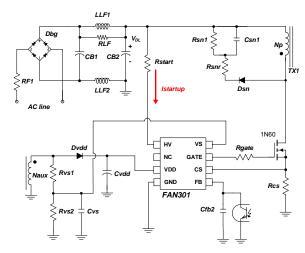


Figure 26. HV Startup Circuit

Operating Current

The operating current has been reduced to 3mA, which results in higher efficiency and reduces the V_{DD} hold-up capacitance requirement. Once FAN301 enters burst mode, the operating current is reduced to $200\mu A$, allowing the power supply to meet the power conservation requirements.

Frequency Hopping

EMI reduction is accomplished by frequency hopping, which spreads the energy over a wider frequency range than the bandwidth measured by the EMI test equipment. FAN301 has an internal frequency-hopping circuit that changes the switching frequency between 41kHz and 49kHz with a period, as shown in Figure 27.

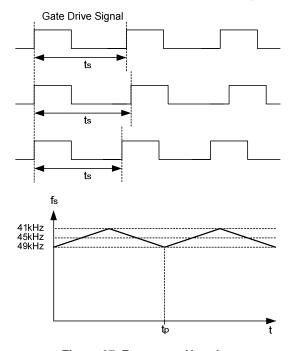


Figure 27. Frequency Hopping

Green-Mode Operation

The proprietary green-mode function provides off-time modulation to linearly decrease the switching frequency, as shown in Figure 28. Under light-load and zero-load conditions, the on-time is limited to provide protection against brownouts and abnormal conditions. Power supplies using FAN301 can meet international restrictions regarding standby power-consumption.

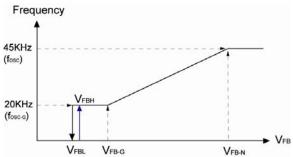


Figure 28. Green-Mode Frequency vs. VFB

Burst-Mode Operation

The power supply enters "burst-mode" in no-load conditions. As shown in Figure 29, when V_{FB} drops below V_{FBL} , the PWM output is shuts off and the output voltage drops at a rate dependent on load current. This causes the feedback voltage to rise. Once V_{FB} exceeds V_{FBH} , the internal circuit starts to provide a switching pulse. The feedback voltage then falls and the process repeats. Burst-mode operation alternately enables and disables switching of the MOSFET, reducing the switching losses in standby mode.

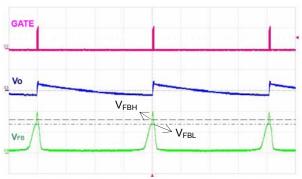


Figure 29. Burst-Mode Operation

Gate Output

The FAN301 BiCMOS output stage is a fast totem-pole gate driver. Cross conduction has been avoided to minimize heat dissipation, increase efficiency, and enhance reliability. The output driver is clamped by an internal 15V Zener diode to protect the power MOSFET transistors against undesired over-voltage gate signals.

Protections

The FAN301 self-protection functions include Over-Voltage Protection (OVP), $V_{\rm S}$ Over-Voltage Protection, Over-Temperature Protection (OTP), and pulse-by-pulse current limit. All the protections are implemented as auto-restart mode. If an abnormal condition occurs, switching is terminated and the MOSFET remains off, causing $V_{\rm DD}$ to drop. When $V_{\rm DD}$ reaches the $V_{\rm DD}$ turn-off voltage of 5V, the internal startup circuit is enabled again, then the supply current drawn from the HV pin charges the hold-up capacitor. When $V_{\rm DD}$ reaches the turn-on voltage of 16V, normal operation resumes. In this manner, the auto-restart alternately enables and disables the switching of the MOSFET until the abnormal condition is eliminated (see Figure 30).

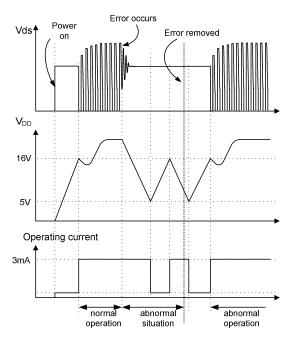


Figure 30. Auto-Restart Operation

Under-Voltage Lockout (UVLO)

The turn-on and turn-off thresholds are fixed internally at 16V and 5V, respectively. During startup, the hold-up capacitor must be charged to 16V through the startup resistor to enable the FAN301. The hold-up capacitor continues to supply $V_{\rm DD}$ until power can be delivered from the auxiliary winding of the main transformer. $V_{\rm DD}$ must not drop below 5V during this startup process. This UVLO hysteresis window ensures that the hold-up capacitor is adequate to supply $V_{\rm DD}$ during startup.

V_{DD} Over-Voltage Clamping

When the V_{DD} voltage exceeds 28V due to abnormal conditions, PWM pulses are disabled until the V_{DD} voltage drops below the UVLO threshold, then start again. Over-voltage conditions are usually caused by open feedback loops.

V_S Over-Voltage Protection

When the V_S voltage exceeds 3V due to abnormal conditions, PWM pulses are disabled until the V_{DD} voltage drops below the UVLO threshold, then start again. V_S over-voltage conditions are usually caused by open feedback loops or VS pin resistor abnormality.

Over-Temperature Protection (OTP)

The FAN301 temperature-sensing circuit shuts down PWM output if the junction temperature exceeds 140° C (T_{OTP}). The PWM pulses are disabled until the junction temperature drops below the $T_{OTP-RESTART}$ threshold.

Leading-Edge Blanking

Each time the power MOSFET is switched on, a turn-on spike occurs at the sense resistor. To avoid premature termination of the switching pulse, a 350ns leading-edge blanking time is built in, which allows conventional RC filtering to be omitted. During this blanking period, the current-limit comparator is disabled and cannot switch off gate driver.

Built-in Slope Compensation

The sensed voltage across the current-sense resistor is used for current-mode control and pulse-by-pulse current limiting. Built-in slope compensation improves stability and prevents sub-harmonic oscillations due to peak-current mode control. The FAN301 has a synchronized, positively-sloped ramp built-in at each switching cycle.

Noise Immunity

Noise from the current sense or the control signal can cause significant pulse-width jitter, particularly in continuous-conduction mode. While slope compensation helps alleviate these problems, further precautions should still be taken. Good placement and layout practices should be followed. Avoiding long PCB traces and component leads, locating compensation and filter components near the FAN301, and increasing the power MOS gate resistance are advised.

Typical Application Circuit

Application	Fairchild Devices	Input Voltage Range	Output	Output DC Cable
Cell Phone Charger	FAN301	90~264V _{AC}	5V/0.89A	AWG26, 1.8 Meter

Features

- High efficiency (>68.17% at full load) meeting Energy Star V2.0 regulation with enough margin
- Low standby power <15mW at no-load condition
- Tight output regulation (CV:±5%, CC:±5%)

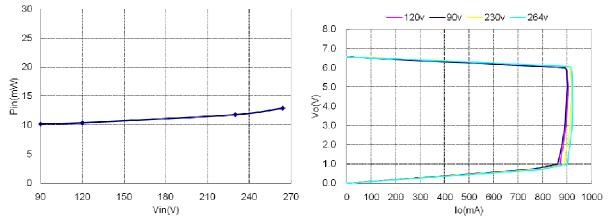


Figure 31. Measured Standby Power and Output Regulation

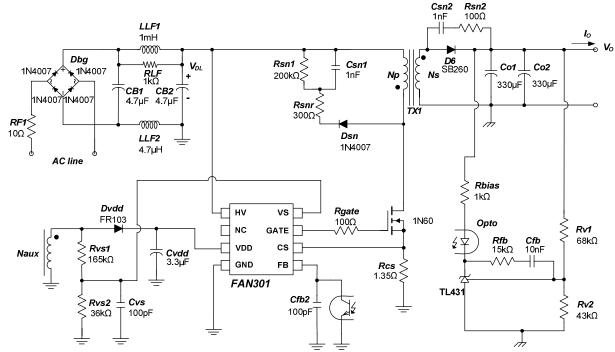


Figure 32. Schematic of Typical Application Circuit

Typical Application Circuit (Continued)

Transformer Specification

Core: EE16Bobbin: EE16

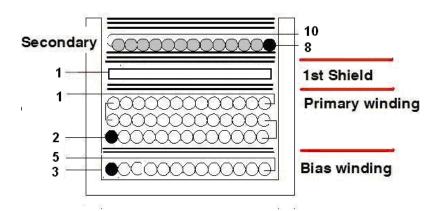


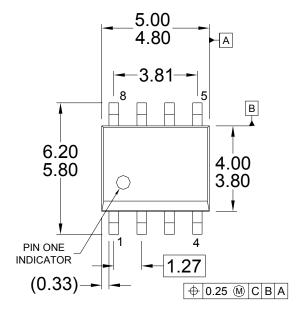
Figure 33. Transformer Diagram

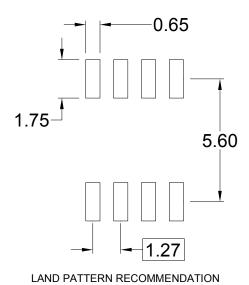
NO	TERMINAL		WIRE	To	
NO.	s	F	WIKE	Ts	
W1	3	5	2UEW 0.25*1	27	
W2	2	1	2UEW 0.15*1	130	
W3	1	-	COPPER SHIELD	1.1	
W4r	8	10	TEX-E 0.4*1	12	
			CORE ROUNDING TAPE	3	

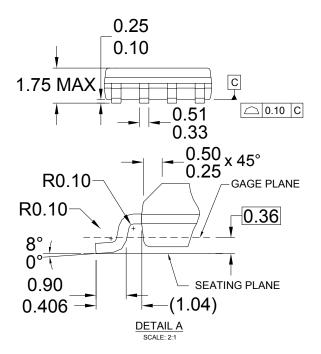
Primary-Side Inductance=2.3mH \pm 5%

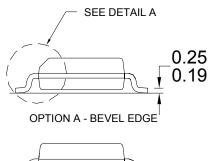
Primary-Side Effective Leakage<80 μ H ± 5%

Physical Dimensions











NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M.
- E) DRAWING FILENAME: M08AREV13

Figure 34. 8-Pin SOP8 Package

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/.





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

CorePOWER™ Green FPS™ e-Series™

CROSSVOLT™ Gmax™

CTL™ GTO™

Current Transfer Logic™ IntelliMAX™

DEUXPEED® ISOPLANAR™

Dual Cool™ MegaBuck™

EcoSPARK® MICROCOUPLER™

EfficientMax™ MicroFet™

ESBC™ MicroPak™

MicroPak™

MicroPak™

Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™

FETBench™ FlashWriter®* FPS™ Power-SPM™ PowerTrench® PowerXS™

Programmable Active Droop™ OFFT®

QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™
SMART START™
SPM®
STEALTH™
SuperFET™
SuperSOT™.3
SuperSOT™.6
SuperSOT™.8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM **
GENERAL
The Power Franchise

power'
franchise
TinyBoost™
TinyBuck™
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TriFault Detect™
TRUECURRENT™*

SerDes"
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
XS™

uSerDes™

MillerDrive™

MotionMax™

OptoHiT™

PDP SPM™

Motion-SPM™

OPTOLOGIC®

OPTOPLANAR®

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a)
 are intended for surgical implant into the body or (b) support or
 sustain life, and (c) whose failure to perform when properly used in
 accordance with instructions for use provided in the labeling, can be
 reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Definition of Terms					
Datasheet Identification	Product Status	Definition			
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.			
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.			

Rev. 149

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.